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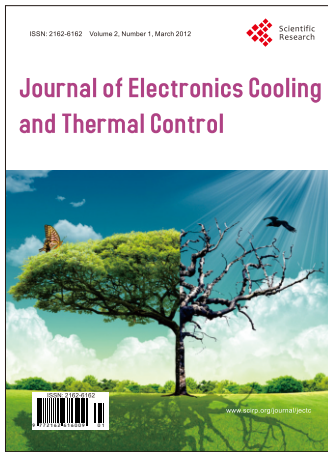
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This journal invites original research and review papers that address the following issues. Topics of interest include, but are not limited to:

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- Base board design and material structure
- Control scenario
- Fan design and performance
- Forced convection heat transfer
- Heat storage
- High heat conductive materials
- Insulation
- Interface thermal contact performance
- Natural convection heat transfer
- Phase changing heat transfer
- Phonon
- Radiation
- Spray cooling
- Temperature stability

Technologies based on these transport processes such as

- Enhanced heat/mass transfer in precision-, micro-electronics, information technology
- Heat pipe
- MEMS (Micro-Electro-Mechanical-Systems) and NEMS (Nano-Electro-Mechanical-Systems)
- Various electronic devices, etc.

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